

Coaxlink Mono CXP-12 LH

One-connection CoaXPress CXP-12 frame grabber



At a Glance

- One CoaXPress CXP-12 connection: 1,250 MB/s camera bandwidth
- PCIe 3.0 (Gen 3) x4 bus: 3,300 MB/s bus bandwidth
- Low-profile card. Delivered with standard and low-profile brackets
- · Passive (fanless) heatsink
- Feature-rich set of 10 digital I/O lines
- Extensive camera control functions
- Memento Event Logging Tool

Benefits

Low-profile PCIe card

• Delivered with standard and low-profile brackets

PCIe 3.0 (Gen 3) x4 bus

• 3,300 MB/s sustained bus bandwidth

Acquire images from the fastest and highest resolution cameras

- Highest data acquisition rate in the industry
- 12.5 Gbit/s (1,250 MB/s) bandwidth from camera to host PC memory

Power over CoaXPress

- Power over CoaXPress: Feed your camera up to 25 W under 24 VDC with automatic device detection, measurement and overload protection.
- Voltage and current measurement is possible, allowing validation and performance deviation monitoring.

Long cable support

- 40 meters at CXP-12 speed (12.5 Gbps)
- 72 meters at CXP-6 speed (6.25 Gbps)
- 100 meters at CXP-3 speed (3 Gbps)

Use standard coaxial cables

- A single inexpensive cable for data transfer, camera control, trigger and power supply
- Top reliability and flexibility, performs in the harshest environments

Micro-BNC (HD-BNC™) connectors for reliable connection

- Trusted push and turn, bayonet-style positive lock
- Allows for quick and easy connects and disconnects

Memento Event Logging Tool

- Memento is an advanced development and debugging tool available for Coaxlink cards.
- Memento records an accurate log of all the events related to the camera, the frame grabber and its driver as well as the application.
- It provides the developer with a precise timeline of time-stamped events, along with context information and logic analyzer view.
- It provides valuable assistance during application development and debugging, as well as during machine operation.

Direct GPU transfer

- Sample programs for AMD DirectGMA and NVIDIA (CUDA) available.
- Direct GPU transfer eliminates unnecessary system memory copies, lowers CPU overhead, and reduces latency, resulting in significant performance improvements in data transfer times for applications.
- Direct capture of image data to GPU memory is available using AMD's DirectGMA. Compatible with AMD FirePro W5x00 and above and all AMD FirePro S series products.

General purpose I/O lines

- Compatible with a wide range of sensors and motion encoders.
- High-speed differential inputs: Quadrature motion encoder support up to 5 MHz.
- Isolated current-sense inputs: 5V, 12V, 24V signaling voltages accepted, up to 50 kHz, individual galvanic isolation up to 250VDC and 170VAC RMS.
- Isolated contact outputs.
- High-speed 5V-compliant TTL inputs/ LVTTL outputs.

High-performance DMA (Direct Memory Access)

- Direct transfer into user-allocated memory and hardware boards that expose PCI addresses
- Hardware scatter-gather support
- 64-bit addressing capability

Area-scan triggering capabilities

- A trigger is used to start the acquisition when the part is in position. Hardware triggers come from the Coaxlink's I/O lines. Software triggers come from the application.
- An optional trigger delay is available to postpone the acquisition for a programmable time.
- A trigger decimation function allows to skip some of the triggers.
- Camera exposure control allows the application to control the exposure time of the camera.
- When the acquisition starts, at the appropriate timing, the Coaxlink board generates a signal to control an illumination device connected to one of its output lines.

Compatible with eGrabber

- eGrabber Studio: eGrabber's new interactive evaluation and demonstration application
- Genicam Browser: An application giving access to the Genicam features exposed by the GenTL Producer(s)
- GenTL Console: A command-line tool giving access to the functions and commands exposed by the Euresys GenTL Producer

Compliant with Genicam

Including support for

- GenApi
- The Standard Feature Naming Convention (SFNC)
- GenTL

Windows, Linux and macOS drivers available

Including support for Intel 32-bit and 64-bit platforms as well as ARM 64-bit platforms

Applications

Machine Vision for the Electronic Manufacturing Industry

- High speed image acquisition for AOI, 3D SPI, 3D lead/ball inspection machines.
- Very high resolution line-scan image acquisition for Flat Panel Display inspection and solar cell inspection
- Mark inspection

Machine Vision for the General Manufacturing Industries

- High frame rate image acquisition for inspection machines
- Line-scan image acquisition for surface inspection machines
- Line-scan image acquisition for textile inspection
- Image acquisition for robots

Machine Vision for the Printing Industry

• High speed line-scan image acquisition for printing inspection machines

Video Acquisition and Recording

High-frame-rate video acquisition for motion analysis and recording

Video Monitoring, Surveillance & Security

• Transmission and acquisition of high-definition video over long coaxial cables for traffic surveillance, monitoring and control

Specifications

Mechanical

Format	Low profile, half length, 4-lane PCI Express card
Cooling method	Air-cooling, fanless
Mounting	 For insertion in a 4-lane or higher, PCI Express card slot.
	 Delivered with standard- and low-profile brackets for insertion in a standard- or a low- profile chassis.

- Bi-color red/green LED - CoaXPress Host connector indicator • 'FPGA STATUS LAMP' on PCB: - Bi-color red/green LED - FPGA status indicator • 'BOARD STATUS LAMP' on PCB: - Bi-color red/green LED - Board status indicator Switches * 'RECOVERY' on card PCB: - 3-pin 1-row 0.1" header - Firmware emergency recovery Dimensions L 167.65 mm x H 68,90 mm L 6.6 in x H 2.71 in Weight 160 g, 5.64 oz Host bus Standard PCI Express 3.0 Link width - 4 lanes - 1 lane or 2 lanes with reduced performance Link speed - 8.0 GT/s (PCIe 3.0) - 5.0 GT/s (PCIe 2.0) with reduced performance	Connectors	• 'A' on bracket:
• 'EXTERNAL I/O 1' on bracket:		 Micro-BNC female connector
- 15-pin 3-row high-density female sub-D connector - I/O lines and power output - I'NTERNAL I/O 1' on PCB: - 26-pin 2-row 0.1" pitch pin header with shrouding - I/O lines and power output - I'/O EXTENSION' on PCB: - 26-pin 2-row 0.5" pitch pin header with shrouding - I/O extension lines and power output - I'AUXILIARY POWER INPUT' on module: - 6-pin PEG power socket - 12 VDC power input for PoCXP camera(s) and I/O power - I'C2C-LINK' on module: - 6-pin 2-row 0.1" header - Card to card link LED indicators - I'A' on bracket: - Bi-color red/green LED - CoaXPress Host connector indicator - I'PGA STATUS LAMP' on PCB: - Bi-color red/green LED - FPGA STATUS LAMP' on PCB: - Bi-color red/green LED - Board status indicator - I'BOARD STATUS LAMP' on PCB: - Bi-color red/green LED - Board status indicator Switches - RECOVERY on card PCB: - 3-pin 1-row 0.1" header - Firmware emergency recovery Dimensions - L6.6 in x H 2.71 in Weight - 160 g, 5.64 oz Host bus Standard - PCI Express 3.0 - Link width - 4 lanes - 1 lane or 2 lanes with reduced performance - Elink speed - 8.0 GT/s (PCIe 3.0) - 5.0 GT/s (PCIe 3.0) - 5.0 GT/s (PCIe 2.0) with reduced performance		 CoaXPress host interface
- I/O lines and power output • 'INTERNAL I/O 1' on PCB: - 26-pin 2-row 0.1" pitch pin header with shrouding - I/O lines and power output • 'I/O EXTENSION' on PCB: - 26-pin 2-row 0.05" pitch pin header with shrouding - I/O extension lines and power output • 'AUXILIARY POWER INPUT' on module: - 6-pin PEG power socket - 12 VDC power input for PoCXP camera(s) and I/O power • 'C2C-LINK' on module: - 6-pin 2-row 0.1" header - Card to card link LED indicators • 'A' on bracket: - Bi-color red/green LED - CoaXPress Host connector indicator • 'FPGA STATUS LAMP' on PCB: - Bi-color red/green LED - FPGA status indicator • 'BOARD STATUS LAMP' on PCB: - Bi-color red/green LED - Board status indicator • 'BOARD STATUS LAMP' on PCB: - Bi-color red/green LED - Board status indicator Switches * RECCOVER' on card PCB: • 3-pin 1-row 0.1" header • Firmware emergency recovery Dimensions L 6.6 in x H 2.71 in Weight 160 g, 5.64 oz Host bus Standard PCI Express 3.0 Link width • 4 lanes • 1 lane or 2 lanes with reduced performance Link speed • 8.0 GT/s (PCle 2.0) • 5.0 GT/s (PCle 2.0) with reduced performance		• 'EXTERNAL I/O 1' on bracket:
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• 5.0 GT/s (PCIe 2.0) with reduced performance		• 1 lane or 2 lanes with reduced performance
· · · · · · · · · · · · · · · · · · ·	Link speed	• 8.0 GT/s (PCle 3.0)
Maximum payload size 512 bytes		• 5.0 GT/s (PCIe 2.0) with reduced performance
	Maximum payload size	512 bytes
DMA 32- and 64-bit	DMA	32- and 64-bit
Peak delivery bandwidth 3,900 MB/s	Peak delivery bandwidth	3,900 MB/s
Effective (sustained) delivery 3,350 MB/s (Host PC motherboard dependent) bandwidth	Effective (sustained) delivery	
	Power consumption	Typ. 11.5 W (3 W @ 3.3 V + 8.5 W @ 12 V), excluding camera and I/O power output
	Power consumption	Typ. 11.5 W (3 W @ 3.3 V + 8.5 W @ 12 V), excluding camera and I/O power output

Camera / video inputs

Camera / video inputs	
Interface standard(s)	CoaXPress 1.0, 1.1, 1.1.1 and 2.0
Connectors	One micro-BNC 75 Ohms (also known as HD-BNC™) CXP-12
Status LEDs	One CoaXPress Host connection status LED per connection
Number of cameras	One 1-connection area-scan camera
Maximum aggregated camera data transfer rate	12.5 Gbit/s (1,250 MB/s)
Supported CXP down-connection speeds	1.25 GT/s (CXP-1), 2.5 GT/s (CXP-2), 3.125 GT/s (CXP-3), 5 GT/s (CXP-5), 6.25 GT/s (CXP-6), 10.0 GT/s (CXP-10), and 12.5 GT/s (CXP-12)
Supported CXP up-connection	• Low-speed 20.83 Mbps (CXP-1 to CXP-6)
speeds	• Low-speed 41.66 Mbps (CXP-10, CXP-12)
Number of CXP data streams (per camera)	1 data stream per camera
Maximum CXP stream packet size	16,384 bytes
PoCXP (Power over CoaXPress)	PoCXP Safe Power:
	25 W of 24V DC regulated power
	 PoCXP Device detection and automatic power-on
	 Overload and short-circuit protections
	On-board 12V to 24V DC/DC converter
	 A +12V power source must be connected to the AUXILIARY POWER INPUT connector using a 6-pin PEG cable
Camera types	Area-scan cameras:
	 Grayscale and color (RGB and Bayer CFA)
	Single-tap (1X-1Y) progressive-scan
Camera pixel formats supported	Raw, Monochrome, Bayer, RGB, and RGBA (PFNC names):
	• Raw
	 Mono8, Mono10, Mono12, Mono14, Mono16
	• BayerXX8, BayerXX10, BayerXX12, BayerXX14, BayerXX16 where XX = GR, RG, GB, or BG
	• RGB8, RGB10, RGB12, RGB14, RGB16
	• RGBA8, RGBA10, RGBA12, RGBA14, RGBA16
	• YCbCr601_422_8, YCbCr601_422_10
	• YCbCr709_422_8, YCbCr709_422_10
	• YUV422_8, YUV422_10
Area-scan camera control	
Trigger	 Precise control of asynchronous reset cameras, with exposure control.
	 Support of camera exposure/readout overlap.
	 Support of external hardware trigger, with optional delay and trigger decimation.
Strobe	 Accurate control of the strobe position for strobed light sources.
	Support of early and late strobe pulses.
On-board processing	
On-board memory	512 MB
Image data stream processing	 Unpacking of 10-/12-/14-bit to 16-bit with selectable justification to LSb or MSb
	Optional swap of R and B components
	Little endian conversion

Input LUT (Lookup Table)	Only available for monochrome cameras:
	• 8 to 8 bits
	• 10 to 8, 10 or 16 bits
	• 12 to 8, 12 or 16 bits
Data stream statistics	Measurement of:
	– Frame rate (Area-scan only)
	– Line rate
	– Data rate
	Configurable averaging interval
Event signaling and counting	 The application software can be notified of the occurrence of various events:
	 Standard event: the EVENT_NEW_BUFFER event notifies the application of newly filled buffers
	 A large set of custom events
	Custom events sources:
	− I/O Toolbox events
	 Camera and Illumination control events
	 CoaXPress data stream events
	 CoaXPress host interface events
	 Each custom event is associated with a 32-bit counter that counts the number of occurrences
	 The last three 32-bit context data words of the event context data can be configured with event-specific context data:
	 Event-specific data
	 State of all System I/O lines sampled at the event occurrence time
	 Value of any event counter
General Purpose Inputs ar Outputs	nd
Number of lines	10 I/O lines:
Trainiber of times	• 2 differential inputs (DIN)
	• 2 singled-ended TTL inputs/outputs (TTLIO)
	• 4 isolated inputs (IIN)*
	• 2 isolated outputs (IOUT)*
	NOTE: Only 2 IIN and 1 IOUT lines are available on the EXTERNAL I/O connector.
	NOTE: The number of I/O lines can be extended using I/O modules attached to the I/O EXTENSION connector.
Heago	Any I/O input lines can be used by any LIN tool of the I/O Toolbox
Usage	 Selected pairs of I/O input lines can be used by any QDC tool of the I/O toolbox to decoded A/B signals of a motion encoder
	 The LIN and QDC tools outputs can be further processed by the other tools (DIV, MDV, DEL) of the I/O toolbox to generate any of the following "trigger" events:
	 The "cycle trigger" of the Camera and Illumination controller The "cycle sequence trigger" of the Camera and Illumination controller

Electrical specifications	 DIN: High-speed differential inputs compatible with ANSI/EIA/TIA-422/485 differential line drivers and complementary TTL drivers
	 TTLIO: High-speed 5V-compliant TTL inputs or LVTTL outputs, compatible with totempole LVTTL, TTL, 5V CMOS drivers or LVTTL, TTL, 3V CMOS receivers
	 IIN: Isolated current-sense inputs with wide voltage input range up to 30V, compatible with totem-pole LVTTL, TTL, 5V CMOS drivers, RS-422 differential line drivers, potential free contacts, solid-state relays and opto-couplers
	IOUT: Isolated contact outputs compatible with 30V / 100mA loads
Filter control	 Glitch removal filter available on all System I/O input lines
	Configurable filter time constants:
	$^-$ for DIN and TTLIO lines: 50 ns, 100 ns, 200 ns, 500 ns, 1 μs
	– for IIN lines: 500 ns, 1 μs, 2 μs, 5 μs, 10 μs
Polarity control	Yes
Power output	Non-isolated, +12V, 1A, with electronic fuse protection
I/O Toolbox tools	The I/O Toolbox is a configurable interconnection of tools that generates events (usually triggers) from input lines. The composition of the toolset is product- and firmware-dependent.
	 Line Input tool (LIN): Edge detector delivering events on rising or falling edges of any selected input line.
	 Quadrature Decoder tool (QDC): A composite tool including:
	 A quadrature edge detector delivering events on selected transitions of selected pairs of input lines.
	 An optional backward motion compensator for clean line-scan image acquisition when the motion is unstable.
	 A 32-bit up/down counter for delivering a position value.
	 Divider tool (DIV): to generate an event every nth input events from any I/O toolbox event source.
	 Multiplier/divider tool (MDV): to generate m events every d input events from any I/O toolbox event source.
	 Delay tool (DEL): to delay up to 16 events from one or two I/O toolbox event sources, by a programmable time or number of motion encoder ticks (any QDC events).
	 User Actions Scheduler tool (UAS): to delegate the execution of User Actions at a scheduled time or encoder position. Possible user actions include setting low/high/toggle any bit of the User Output Register or generation of any User Events.
I/O Toolbox composition	8 LIN, 1 QDC, 1 DIV, 1 MDV, 2 DEL, 1 UAS
C2C-Link	
Description	 Accurate synchronization of the trigger and the start-of-exposure of multiple grabber- controlled area-scan cameras.
	 Accurate synchronization of the start-of-cycle, start-of-scan and end-of-scan of multiple grabber-controlled line-scan cameras.

Specification	C2C-Link synchronizes cameras connected to:
Specification	- the same card
	 to different cards in the same PC (requires an accessory cable such as the "3303 C2C-Link Ribbon Cable" or a custom-made C2C-Link cable)
	 to different cards in different PCs (requires one "1636 InterPC C2C-Link Adapter" for each PC and one RJ 45 CAT 5 STP straight LAN cable for each adapter but the last one)
	Maximum distance:
	- 60 cm inside a PC
	 1200 m cumulated adapter to adapter cable length
	Maximum trigger rate:
	 2.5 MHz for configurations using a single PC, or up to 10 PCs and 100 m total C2C-Link cable length
	 200 kHz for configurations up to 32 PCs and 1200m total C2C-Link cable length
	 Trigger propagation delay from master to slave devices:
	 Less than 10 ns for cameras on the same card or on different cards in the same PC
	 Less than 265 ns for cameras on different cards in different PCs (3 PCs and 40m total C2C-Link cable length)
Software	
Host PC Operating System	• Microsoft Windows 10, 8.1, 7 for x86 (32-bit) and x86-64 (64-bit) processor architectures
	• Linux for x86 (32-bit), x86-64 (64-bit) and aarch64 (64-bit) processor architectures
	 macOS for x86-64 (64-bit) processor architecture
	Refer to release notes for details
APIs	EGrabber class, with C++ and .NET APIs:
	 .NET assembly designed to be used with development environments compatible with .NET frameworks version 4.0 or higher
	GenICam GenTL producer libraries compatible with C/C++ compilers:
	 x86 dynamic library designed to be used with ISO-compliant C/C++ compilers for the development of x86 applications
	• x86_64 dynamic library designed to be used with ISO-compliant C/C++ compilers for the development of x86_64 applications
	 aarch64 dynamic library designed to be used with ISO-compliant C/C++ compilers for the development of aarch64 applications
Environmental conditions	
Operating ambient air temperature	0 to +55 °C / +32 to +131 °F, with minimum 150 LFM (Linear Feet per Minute) required airflow
Operating ambient air humidity	10 to 90% RH non-condensing
Storage ambient air temperature	-20 to +70 °C/ -4 to +158 °F
Storage ambient air humidity	10% to 90% RH non-condensing
Certifications	
Electromagnetic - EMC standards	European Council EMC Directive 2004/108/EC
	United States FCC rule 47 CFR 15
EMC - Emission	• EN 55022:2010 Class B
	FCC 47 Part 15 Class B
EMC - Immunity	• EN 55024:2010 Class B
	• EN 61000-4-3
	• EN 61000-4-4
	• EN 61000-4-6
KC Certification	Korean Radio Waves Act, Article 58-2, Clause 3

Flammability	PCB compliant with UL 94 V-0
RoHS	European Union Directive 2015/863 (ROHS3)
REACH	European Union Regulation 1907/2006
WEEE	Must be disposed of separately from normal household waste and must be recycled according to local regulations
Ordering Information	
Product code - Description	3621-LH - Coaxlink Mono CXP-12 LH
Optional accessories	• 1625 - DB25F I/O Adapter Cable
	• 1636 - InterPC C2C-Link Adapter
	• 3303 - C2C-Link Ribbon Cable
	• 3304 - HD26F I/O Adapter Cable
	• 3610 - HD26F I/O Extension Module TTL-RS422
	 3612 - HD26F I/O Extension Module TTL-CMOS5V-RS422
	• 3614 - HD26F I/O Extension Module - Standard I/O Set



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